

Application Notes 95-DRM

BALVER ZINN[®]
COBAR[®]

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Description product

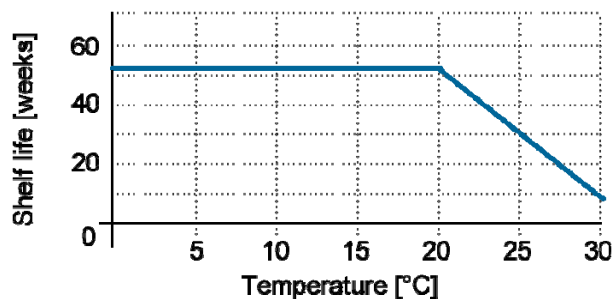
95-DRM is a low VOC flux for wave soldering applications. The flux has very clean residues and good solder properties for use with industrial and consumer applications. The flux has a moderate activation system (ORM0).

See the Product Data Sheet (PDS) for the specification of this product. An up to date version of the PDS for most current products is available through our website at www.cobar.com. See the Material Safety Data Sheet (MSDS) before handling and/or using this product.

Receiving and storage

Exposure to heat, frost or rain should be avoided. Do not leave shipments outside. An air-controlled room usually is adequate for storage. Shelf-life is best guaranteed at temperatures below 20 °C and RH below 70%. Fluxes are shelf-life items and should be managed as a FIFO-supply.

Figure 1: Storage temperature versus shelf-life



Flux that has been exposed to frost should be placed in a room with central heating for at least 4 hours and shackled before use.

Handling

The recommended ambient conditions for applying the flux are 18-25 °C. Prior to use the flux: tank, spray nozzle, fingers, pallets/carriers and tubes should be cleaned properly. If pneumatic air is used to apply the flux, the air must be dry, free of oil and temperature controlled. A water and oil separator for the supplied air is strictly necessary.

It is important to start with components and board materials that meet requirements for solderability and ionic cleanliness.

Flux applications

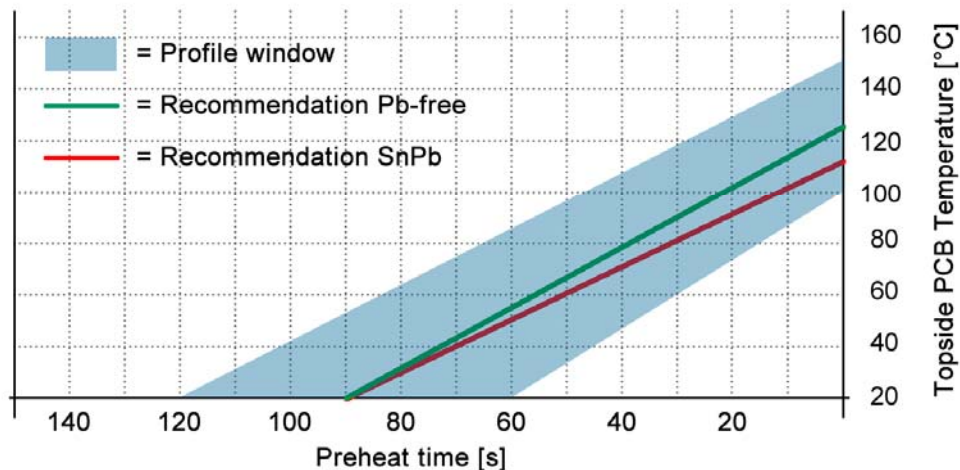
Spray fluxing is the preferred application to apply this flux. Make sure that the unit has a stable and uniform spray-cone. The flux should have the finest droplets at the lowest possible setting for the atomizing air pressure. (Low air pressure gives bigger and unstable droplets; high air pressure cause bouncing effects of the flux against the PCB surface).

Use a scrap/bare board to set-up the spray parameters. Turn the board upside down after spraying for inspection. It is essential that a continuous, uniform spray pattern has been deposited all across the board.

Preheat profile

The top side (component side) board temperature measured at the end of the preheat zone should be between 90-150°C. To ensure a smooth and complete evaporation of the flux a linear profile with a temperature gradient $< 2 \text{ }^\circ\text{C/s}$ is recommended.

Figure 2: Preheat recommendation



Soldering

In order to obtain clean and well-soldered assemblies, a contact time in the solder wave between 2.5 and 4 seconds is recommended. This time is temperature depended. For a typical SnPb process (solder temperature 250 °C) the initial setting is approximately 2.5 seconds. For lead-free (solder temperature 260 °C) up to 4 seconds depending on the application.

Conformal coatings

When properly processed, this flux is compatible with many conformal coatings based on acrylic, polyurethane and silicone resins.

Disclaimer:

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